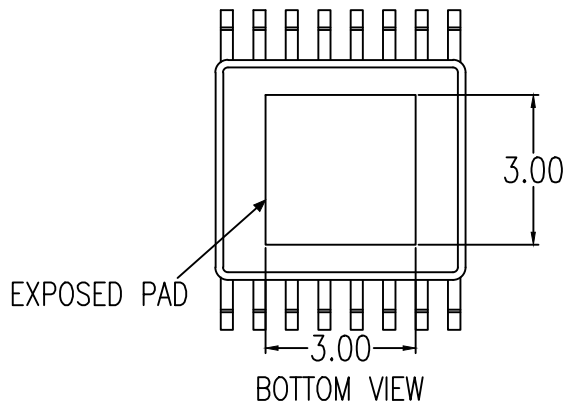
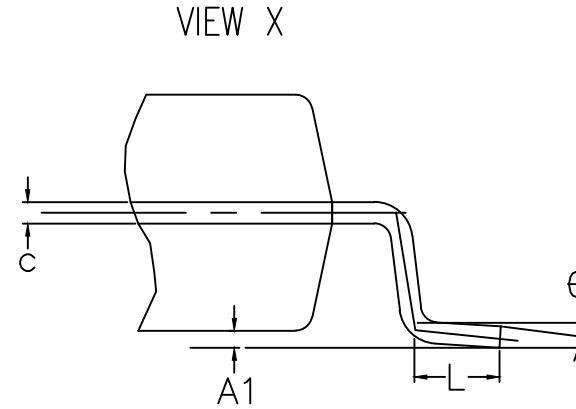
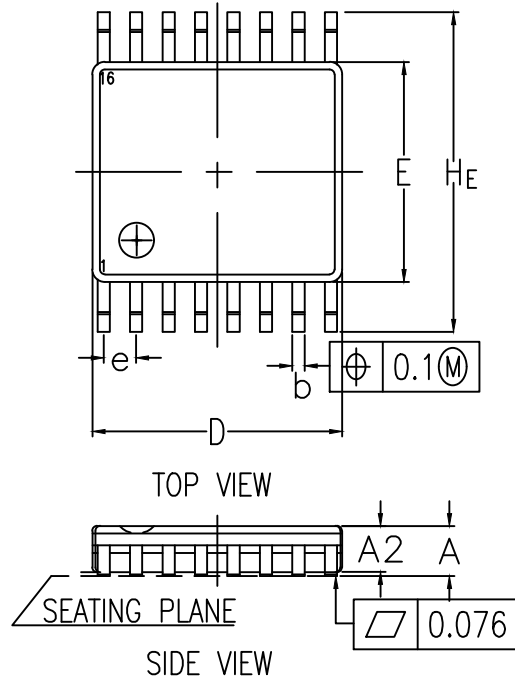


BASED ON JEDEC JEP95: MO-153

DIMENSIONS IN MILLIMETERS

1. DIMENSIONS


DATE CREATED		REVISIONS	
REV	DESCRIPTION	AUTHOR	
9/20/18	00	Revised from PSC-4749 PGG16	Eddie Lee/CM
NOTE: REFER TO DCP FOR OFFICIAL RELEASE DATE			



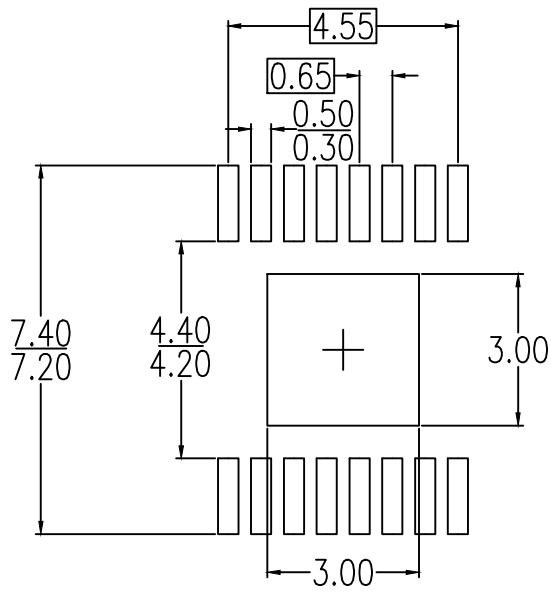
DIMENSIONS	min	max
A	0.90	1.20
A1	0.05	0.15
A2	0.80	1.05
b	0.20	0.30
c	0.10	0.20
D	4.90	5.10
E	4.30	4.50
e	0.65nom	
HE	6.20	6.60
L	0.45	0.75
θ	0°	8°

* WITHOUT MOLD FLASH

- 2. WEIGHT ≤ 0.05 g
- 3. BODY MATERIAL LOW STRESS EPOXY
- 4. LEAD MATERIAL Cu-ALLOY
- 5. LEAD FINISH SOLDER PLATING
- 6. LEAD FORM Z-BENDS


TOLERANCES UNLESS SPECIFIED DECIMAL ANGULAR XX± ± XXX± XXXX±	 6024 Silver Creek Valley Rd San Jose, CA 95138 PHONE: (408) 284-8200 FAX: (408) 284-3572 www.IDT.com	
SIZE	DRAWING No.	REV
C	PSC-4761	00
DO NOT SCALE DRAWING		SHEET 1 OF 2

DATE		REVISIONS	
CREATED	REV	DESCRIPTION	AUTHOR
9/20/18	00	Revised from PSC-4749 PGG16	Eddie Lee/CM
NOTE: REFER TO DCP FOR OFFICIAL RELEASE DATE			



LAND PATTERN DIMENSIONS

NOTE:
1. ALL DIMENSIONS ARE IN MILLIMETERS

TOLERANCES UNLESS SPECIFIED DECIMAL ANGULAR XX± ± XXX± XXXX±		 IDT™ www.IDT.com 6024 Silver Creek Valley Rd San Jose, CA 95138 PHONE: (408) 284-8200 FAX: (408) 284-3572
TITLE ENG16 Package Outline Drawing 4.4mm, Epad 3.0 x 3.0 mm 0.65mm Pitch TSSOP		
SIZE	DRAWING No.	REV
C	PSC-4761	00
DO NOT SCALE DRAWING		SHEET 2 OF 2